PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3668931

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Shing-Yih Shih	12/16/2015

RECEIVING PARTY DATA

Name:	INOTERA MEMORIES, INC.
Street Address:	667, Fuhsing 3rd Rd., Hwa-Ya Technology Park, Guishan Dist.
City:	Taoyuan City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14977645

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/
DATE SIGNED:	12/22/2015

Total Attachments: 2
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Docket No INOP0079USA4

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:
MULTI-CHIP SEMICONDUCTOR PACKAGE WITH VIA COMPONENTS AND METHOD FOR MANUFACTURING THE SAME

As the below named inventor, I hereby declare that:
This declaration is directed to:

☑ The attached application, or

☐ United States application number __________ filed on __________, or

☐ PCT international application number __________ filed on __________

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **INOTERA MEMORIES, INC.** having a postal address of

667, Fuhsing 3rd Rd., Hwa-Ya Technology Park, Guishan Dist., Taoyuan City 333, Taiwan, R.O.C.

(referred to as "ASSIGNEE"below) to I of the sum of One Dollar ($ 1.00), the receipt of which is hereby acknowledged, andfor other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.
IN WINTNESS WHEREOF, I have hereunto set hand and seal this DEC 16 2015 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Shing-Yih Shih** Date: DEC 16 2015

Signature: